Hexcel® Redux® 330MPCU Epoxy film adhesives for the bonding and finishing of composites

Category : Polymer , Adhesive , Film , Thermoset , Epoxy , Epoxy Adhesive

Material Notes:

Redux 330 is a 350°F curing tough film adhesive which is ideally suited to structural bonding, composite to composite bonding, surface finishing, electromagnetic shielding and lightning strike applications. It is available with knitted nylon, matt nylon and metal foils, in a choice of weights to suit the wide range of applications. Redux 330 has excellent structural bonding performance and exceeds the requirements of BMS-8-245.Areal Weights: 0.05, 0.07 psf.Features: Ideal for composite to composite bonding (no metallic fiber); Suitable for co-cure with 350°F prepreg systems; Good structural performance and service temperature to 270°F; Low volatile content (solventless production process); Excellent environmental resistance; High toughness; Light tack and good drapability; Contains carrier for glueline thickness control and for improved adhesive handling.Applications: Shielding and Lightning Strike Protection Adhesive Foils

Order this product through the following link:
http://www.lookpolymers.com/polymer_Hexcel-Redux-330MPCU-Epoxy-film-adhesives-for-the-bonding-and-finishing-of-composites.php

Processing Properties	Metric	English	Comments
Shelf Life	6.00 Month @Temperature -17.8 °C	6.00 Month @Temperature 0.000 °F	

Descriptive Properties	Value	Comments
Carrier/Foil	Perforated and expanded Copper foil	

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